

IN THE CLAIMS:

1. (currently amended) A method for producing an electrical double layer capacitor, comprising the steps of:

assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an electrolyte containing a supporting salt, a separator, and a gasket to form a coin- or button-type electrical double layer capacitor; and

heating the assembled coin- or button-type electrical double layer ~~capacitor~~ capacitor so that a temperature profile of the heating step is approximately the same as a temperature profile of reflow soldering; and welding an outer connection terminal to the heated assembled coin- or button-type electrical double layer capacitor.

2. (canceled)

3. (previously presented) A method for producing an electrical double layer capacitor as claimed in claim 1; wherein the heating step comprises heating the assembled coin- or button-type electrical double layer capacitor at a temperature in a range of 180 to 300 °C.

4. (currently amended) A method of mounting an electrical double layer capacitor on a circuit substrate, comprising the steps of:

providing a circuit substrate;

assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an electrolyte containing a supporting salt, a separator, and a gasket to form a coin- or button-type electrical double layer capacitor;

heating the assembled coin- or button-type electrical double layer capacitor;

welding an outer connection terminal to the heated assembled coin- or button-type electrical double layer capacitor;

arranging the heated assembled coin- or button-type electrical double layer capacitor on the circuit substrate;

and

reflow soldering the heated assembled coin- or button-type electrical double layer capacitor on the circuit substrate using the outer connection terminal, a temperature profile of the reflow soldering step being approximately the same as a temperature profile of the heating step.

5. - 11. (canceled)

33. (previously presented) A method according to claim 1; wherein the assembling step comprises assembling together the components by caulk sealing the components.

34. (previously presented) A method according to claim 4; wherein the assembling step comprises assembling together the components by caulk sealing the components.

35. (previously presented)

36. (currently amended) A method for producing an electrical double layer capacitor, comprising the steps of: assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an electrolyte containing a supporting salt, a separator, and a gasket to form a coin- or button-type an electrical double layer capacitor containing a foreign substance; and heating the assembled coin- or button-type electrical double layer capacitor to remove at least a substantial amount of the foreign substance contained in the assembled coin- or button-type electrical double layer capacitor, a temperature profile of the heating step being approximately the same as a temperature profile of reflow soldering; and welding a connection terminal to the heated assembled coin- or button-type electrical double layer capacitor.

37. (canceled)

38. (previously presented) A method according to claim 36; wherein the assembling step comprises assembling together the components by caulk sealing the components.

39. (canceled)

40. (canceled)

41. (previously presented) A method according to claim 36; wherein the heating step comprises heating the assembled electrical double layer capacitor at a temperature in a range of 180 to 300 °C.

42. (previously presented) A method according to claim 36; further comprising the step of marking the heated assembled electrical double layer capacitor to distinguish the heated assembled electrical double layer capacitor from an assembled electrical double layer capacitor which has not been heated.

43. (currently amended) A method of mounting an electrical double layer capacitor on a circuit substrate, comprising the steps of: providing a circuit substrate; assembling together components comprised of a positive electrode, a negative electrode, a non-aqueous solvent, an

electrolyte containing a supporting salt, a separator, and a gasket to form a coin- or button-type electrical double layer capacitor containing a foreign substance; heating the assembled coin- or button-type electrical double layer capacitor to remove at least a substantial amount of the foreign substance contained in the assembled coin- or button-type electrical double layer capacitor; welding a connection terminal to the heated assembled coin- or button-type electrical double layer capacitor; arranging the heated assembled coin- or button-type electrical double layer capacitor on the circuit substrate using the welded connection terminal; and reflow soldering the coin- or button-type heated assembled electrical double layer capacitor on the circuit substrate, a temperature profile of the reflow soldering step being approximately the same as a temperature profile of the heating step.

44. (canceled)

45. (previously presented) A method according to claim 43; wherein the assembling step comprises assembling together the components by caulk sealing the components.

46. (canceled)

47. (canceled)

48. (previously presented) A method according to claim 43; wherein the heating step comprises heating the assembled electrical double layer capacitor at a temperature in a range of 180 to 300 °C.

49. - 54. (canceled)

55. (currently amended) A method according to claim ~~42; 43;~~ further comprising the step of marking the heated assembled electrical double layer capacitor to distinguish the heated assembled electrical double layer capacitor from an assembled electrical double layer capacitor which has not been heated.